



Material Content Data Sheet



Sales Product Name	BGA 825L6S E6327			Issued		30. April 2015		
MA#	MA001056000							
Package	PG-TSLP-6-3			Weight*		0.83 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.214	25.94	25.94	259441	259441
bumps	noble metal	silver	7440-22-4	0.000	0.00		17	
	non noble metal	tin	7440-31-5	0.001	0.07		739	
	non noble metal	copper	7440-50-8	0.006	0.73	0.80	7332	8088
leadframe	non noble metal	nickel	7440-02-0	0.110	13.34	13.34	133407	133407
encapsulation	organic material	carbon black	1333-86-4	0.002	0.28		2804	
	plastics	epoxy resin	-	0.067	8.13		81323	
	inorganic material	silicondioxide	60676-86-0	0.394	47.69	56.10	476721	560848
leadfinish	noble metal	gold	7440-57-5	0.011	1.28	1.28	12841	12841
plating	noble metal	silver	7440-22-4	0.021	2.53	2.53	25273	25273
ubm	non noble metal	copper	7440-50-8	0.000	0.01		67	
	non noble metal	titanium	7440-32-6	0.000	0.00		23	
	non noble metal	tungsten	7440-33-7	0.000	0.00	0.01	12	102
*deviation	< 10%	Sum in total:			100.00			1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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